

Yasuharu UOMORI et al.

Docket No. 010610

REMARKS

The above proposed amendment is submitted to place the claims in substantially the same condition as the claims which have been amended under Article 19 in the International Application PCT/JP99/00940 and to remove improper multiple dependent claims. . Early and favorable action is awaited.

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

In the event there are any additional fees required, please charge our Deposit Account No. 01-2340.

Respectfully submitted,

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Enclosures: Substitute pages 4, 5, 5/1, 15 and 15/1.

VERSION WITH MARKINGS TO SHOW CHANGES MADE

Claims 1 and 6 have been amended as follows:

1. (As amended) A cooler for an electronic device which cools a heating element provided on the electronic device by circulating a cooling liquid, which comprises:
- a substrate;
- a liquid cooling mechanism composed of
- a heat sink formed in a flat shape [and having] to have a heat-receiving face at [one] a surface thereof intended to be in contact with said [electronic device] heating element and having a liquid channel formed therein,
- a pump portion [composed of] having an impeller rotatably provided in a housing formed in a flat shape [and having an impeller and rotatably provided therein, and metal pipes each connecting said liquid channel to said pump portion, and] within said substrate to circulate said cooling liquid,
- metal pipes for circulating said cooling liquid therethrough;
- a forcible air cooling mechanism composed of
- a radiating fin provided on the outer surface of said metal pipes[,] and
- a fan [which] to cool[s] said radiating fin and said housing,
- said pump portion of the liquid cooling mechanism and said fan of the forcible air cooling mechanism being [unified with each other] provided on the substrate in a vertically aligned positional relationship such that said liquid cooling mechanism and said forcible air cooling

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mechanism are unified.

6. (Amended) The cooler for an electronic device as claimed in Claim 4 [or 5], wherein said motor substrate is made of an insulating plate having a coil formed on the surface thereof, said fan is in the form of a thin plate having a plurality of bent blades on the periphery of a thin plate having a rotation axis at the middle portion thereof, and said motor substrate, said fan and said pump portion in a flat form are laminated on each other.

TECHNICAL DRAWING
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